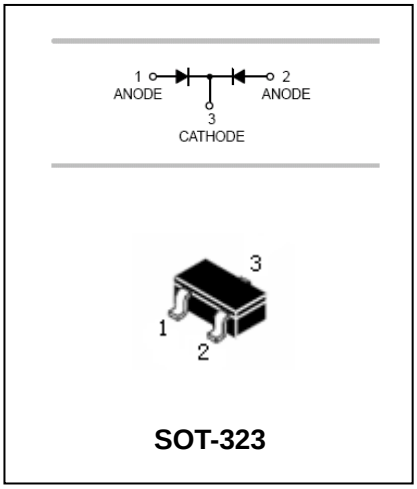
Dual surface mount switching diode **DAN202U**

FEATURES

Lead-free

- For types of packaging are available.
- High speed switching.
- Suitable for high packing density layout.
- High reliability.



SOT-323

APPLICATIONS

- For general purpose switching applications.

ORDERING INFORMATION

Type No.	Marking	Package Code
DAN202U	N	SOT-323

MAXIMUM RATING @ Ta=25℃ unless otherwise specified

Parameter	**Symbol**	**Limits**	**Unit**
Non-Repetitive Peak reverse voltage	V_{RM}	80	V
Diode reverse voltage	V_R	80	V
Forward continuous Current（peak）	I_F	300	mA
Average forward current	I_O	100	mA
Power Dissipation	P_d	200	mW
Junction temperature	T_j	150	℃
Storage temperature range	T_{stg}	-65 to +150	℃

Dual surface mount switching diode **DAN202U**

ELECTRICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse breakdown voltage	$V_{(BR)R}$	I_R= 100μA	80		V
Reverse voltage leakage current	I_R	V_R=70V		0.1	μA
Forward voltage	V_F	I_F=100mA		1.2	V
Diode capacitance	C_D	V_R=6V f=1MHz		3.5	pF
Reverse recovery time	t_{rr}	V_R=6V,I_F=5mA		4	nS

TYPICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

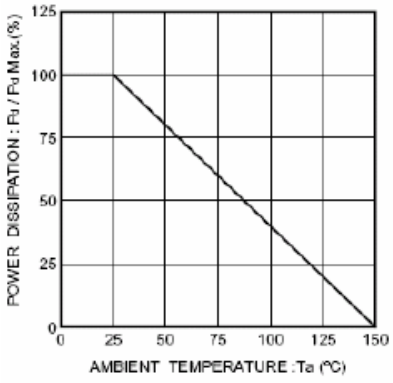


Fig.1 Power attenuation curve

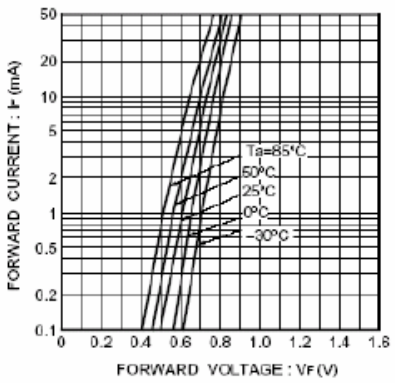


Fig.2 Forward characteristics (P Type)

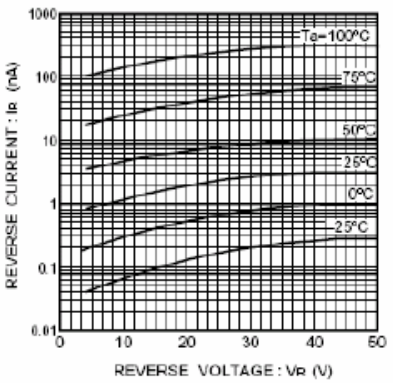


Fig.3 Reverse characteristics (P Type)

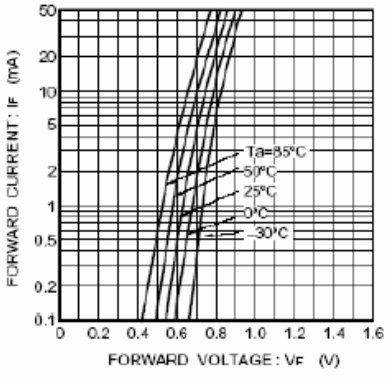


Fig.4 Forward characteristics (N Type)

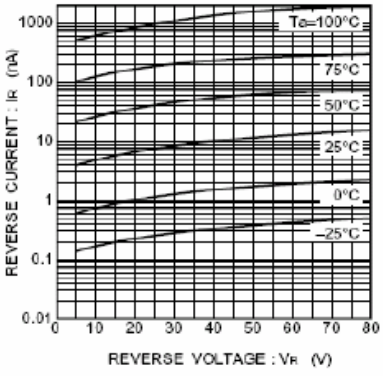


Fig.5 Reverse characteristics (N Type)

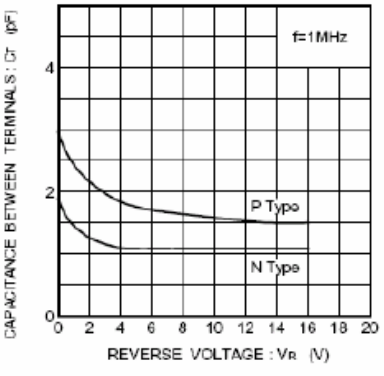
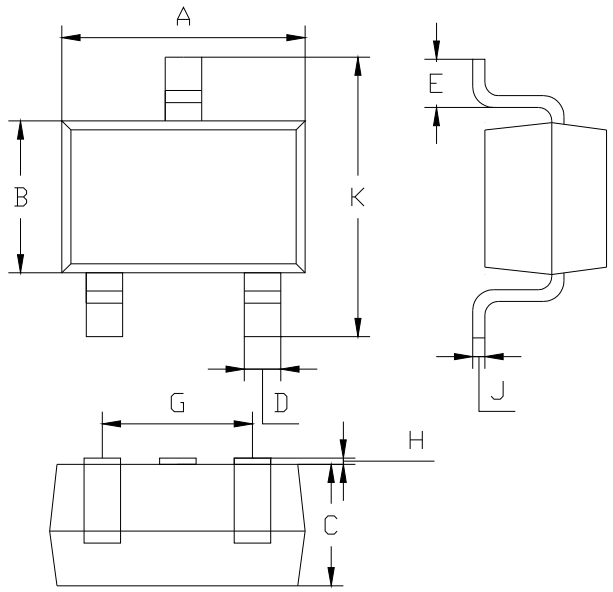


Fig.6 Capacitance between terminals characteristics

Dual surface mount switching diode **DAN202U**

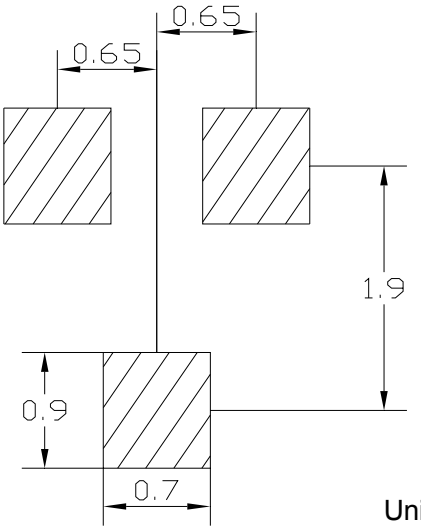
PACKAGE OUTLINE

Plastic surface mounted package SOT-323



SOT-323		
Dim	Min	Max
A	1.8	2.2
B	1.15	1.35
C	1.0Typical	
D	0.15	0.35
E	0.25	0.40
G	1.2	1.4
H	0.02	0.1
J	0.1Typical	
K	2.2	2.4
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
DAN202U	SOT-323	3000/Tape&Reel